# 2 kb I<sup>2</sup>C EEPROM for DDR2 DIMM Serial Presence Detect

### Description

The CAT34C02 is a 2 kb Serial CMOS EEPROM, internally organized as 16 pages of 16 bytes each, for a total of 256 bytes of 8 bits each.

It features a 16-byte page write buffer and supports both the Standard (100 kHz) as well as Fast (400 kHz) I<sup>2</sup>C protocol.

Write operations can be inhibited by taking the WP pin High (this protects the entire memory) or by setting an internal Write Protect flag via Software command (this protects the lower half of the memory).

In addition to Permanent Software Write Protection, the CAT34C02 also features JEDEC compatible Reversible Software Write Protection for DDR2 Serial Presence Detect (SPD) applications operating over the 1.7 V to 3.6 V supply voltage range.

The CAT34C02 is fully backwards compatible with earlier DDR1 SPD applications operating over the 1.7 V to 5.5 V supply voltage range.

### **Features**

- Supports Standard and Fast I<sup>2</sup>C Protocol
- 1.7 V to 5.5 V Supply Voltage Range
- 16-Byte Page Write Buffer
- Hardware Write Protection for Entire Memory
- Software Write Protection for Lower 128 Bytes
- Schmitt Triggers and Noise Suppression Filters on I<sup>2</sup>C Bus Inputs (SCL and SDA)
- Low power CMOS Technology
- 1,000,000 Program/Erase Cycles
- 100 Year Data Retention
- Industrial Temperature Range
- This Device is Pb–Free, Halogen Free/BFR Free and RoHS Compliant\*

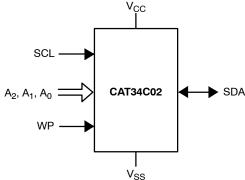


Figure 1. Functional Symbol



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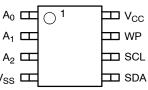
TSSOP-8 Y SUFFIX CASE 948AL TDFN-8 VP2 SUFFIX CASE 511AK





UDFN-8 HU3 SUFFIX CASE 517AX UDFN-8 EP HU4 SUFFIX CASE 517AZ

### **PIN CONFIGURATION**



TSSOP (Y), TDFN (VP2), UDFN (HU3), UDFN (HU4)

For the location of Pin 1, please consult the corresponding package drawing.

### **PIN FUNCTION**

Pin Name	Function
A <sub>0</sub> , A <sub>1</sub> , A <sub>2</sub>	Device Address Input
SDA	Serial Data Input/Output
SCL	Serial Clock Input
WP	Write Protect Input
V <sub>CC</sub>	Power Supply
V <sub>SS</sub>	Ground

### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 14 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**Table 1. ABSOLUTE MAXIMUM RATINGS** 

Parameter	Rating	Unit
Operating Temperature	-45 to +130	°C
Storage Temperature	−65 to +150	°C
Voltage on Any Pin with Respect to Ground (Note 1)	-0.5 to +6.5	V
Voltage on Pin A <sub>0</sub> with Respect to Ground	-0.5 to +10.5	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 2. RELIABILITY CHARACTERISTICS (Note 2)

Symbol	Parameter	Min	Units
N <sub>END</sub> (Note 3)	Endurance	1,000,000	Program/ Erase Cycles
$T_{DR}$	Data Retention	100	Years

<sup>2.</sup> These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

Table 3. D.C. OPERATING CHARACTERISTICS ( $V_{CC} = 1.7 \text{ V to } 5.5 \text{ V}$ ,  $T_A = -40 ^{\circ}\text{C}$  to  $+85 ^{\circ}\text{C}$ , unless otherwise specified.)

Symbol	Parameter	Min	Max	Units	
I <sub>CC</sub>	Supply Current	V <sub>CC</sub> < 3.6 V, f <sub>SCL</sub> = 100 kHz		1	mA
		V <sub>CC</sub> > 3.6 V, f <sub>SCL</sub> = 400 kHz		2	
I <sub>SB</sub>	Standby Current	I/O Pins at GND or V <sub>CC</sub> , V <sub>CC</sub> = 1.7 V		1	μΑ
		I/O Pins at GND or V <sub>CC</sub> , V <sub>CC</sub> > 1.7 V		2	
l <sub>L</sub>	I/O Pin Leakage	Pin at GND or V <sub>CC</sub>		2	μΑ
V <sub>IL</sub>	Input Low Voltage		-0.5	0.3 x V <sub>CC</sub>	V
V <sub>IH</sub>	Input High Voltage		0.7 x V <sub>CC</sub>	V <sub>CC</sub> + 0.5	
V <sub>OL</sub>	Output Low Voltage	$V_{CC} > 2.5 \text{ V, } I_{OL} = 3 \text{ mA}$		0.4	
		V <sub>CC</sub> < 2.5 V, I <sub>OL</sub> = 1 mA		0.2	1

Table 4. PIN IMPEDANCE CHARACTERISTICS ( $V_{CC}$  = 1.7 V to 5.5 V,  $T_A$  = -40°C to +85°C, unless otherwise specified.)

Symbol	Parameter	Parameter Conditions		
C <sub>IN</sub> (Note 4)	SDA I/O Pin Capacitance	DA I/O Pin Capacitance V <sub>IN</sub> = 0 V, f = 1.0 MHz, V <sub>CC</sub> = 5.0 V		pF
	Other Input Pins		6	1
I <sub>WP</sub> (Note 5)	WP Input Current	V <sub>IN</sub> < V <sub>IH</sub> , V <sub>CC</sub> = 5.5 V	130	μΑ
		V <sub>IN</sub> < V <sub>IH</sub> , V <sub>CC</sub> = 3.6 V	120	1
		V <sub>IN</sub> < V <sub>IH</sub> , V <sub>CC</sub> = 1.7 V	80	1
		$V_{IN} > V_{IH}$	2	1

<sup>4.</sup> These parameters are tested initially and after a design or process change that affects the parameter according to appropriate AEC-Q100 and JEDEC test methods.

<sup>1.</sup> The DC input voltage on any pin should not be lower than -0.5 V or higher than  $V_{CC} + 0.5$  V. During transitions, the voltage on any pin may undershoot to no less than -1.5 V or overshoot to no more than  $V_{CC} + 1.5$  V, for periods of less than 20 ns.

<sup>3.</sup> Page Mode, V<sub>CC</sub> = 5 V, 25°C

<sup>5.</sup> When not driven, the WP pin is pulled down to GND internally. For improved noise immunity, the internal pull-down is relatively strong; therefore the external driver must be able to supply the pull-down current when attempting to drive the input HIGH. To conserve power, as the input level exceeds the trip point of the CMOS input buffer (~ 0.5 x V<sub>CC</sub>), the strong pull-down reverts to a weak current source.

Table 5. A.C. CHARACTERISTICS ( $V_{CC}$  = 1.7 V to 5.5 V,  $T_A$  = -40°C to +85°C) (Note 6)

		Stan	Standard		ast	
Symbol	Parameter	Min	Max	Min	Max	Units
F <sub>SCL</sub>	Clock Frequency		100		400	kHz
t <sub>HD:STA</sub>	START Condition Hold Time	4		0.6		μs
t <sub>LOW</sub>	Low Period of SCL Clock	4.7		1.3		μs
tHIGH	High Period of SCL Clock	4		0.6		μs
tsu:sta	START Condition Setup Time	4.7		0.6		μs
thd:dat	Data Hold Time	0		0		μs
tsu:dat	Data Setup Time	250		100		ns
t <sub>R</sub> (Note 7)	SDA and SCL Rise Time		1000		300	ns
t <sub>F</sub> (Note 7)	SDA and SCL Fall Time		300		300	ns
t <sub>SU:STO</sub>	STOP Condition Setup Time	4		0.6		μs
t <sub>BUF</sub>	Bus Free Time Between STOP and START	4.7		1.3		μs
t <sub>AA</sub>	SCL Low to SDA Data Out		3.5		0.9	μs
t <sub>DH</sub>	Data Out Hold Time	100		100		ns
T <sub>i</sub> (Note 7)	Noise Pulse Filtered at SCL and SDA Inputs		100		100	ns
t <sub>SU:WP</sub>	WP Setup Time	0		0		μs
t <sub>HD:WP</sub>	WP Hold Time	2.5		2.5		μs
t <sub>WR</sub>	Write Cycle Time		5		5	ms
t <sub>PU</sub> (Notes 7 & 8)	Power-up to Ready Mode		1		1	ms

<sup>6.</sup> Test conditions according to "A.C. Test Conditions" table.

Table 6. THERMAL CHARACTERISTICS (Air velocity = 0 m/s, 4 layers PCB) (Notes 9 and 10)

Part Number	Package	$\theta_{JA}$	$\theta_{\sf JC}$	Units
CAT34C02Y	TSSOP	64	37	°C/W
CAT34C02VP2	TDFN	92	15	°C/W
CAT34C02HU3	UDFN	101	18	°C/W
CAT34C02HU4	UDFN	101	18	°C/W

<sup>9.</sup>  $T_J = T_A + P_D * \theta_{JA}$ , where:  $T_J$  is the Junction Temperature,  $T_A$  the Ambient Temperature,  $P_D$  the Power dissipation. Example: CAT34C02VP2,  $V_{CC} = 3.0 \text{ V}$ ,  $I_{CC_{max}} = 1 \text{ mA}$ ,  $T_A = 85^{\circ}\text{C}$ :  $T_J = 85^{\circ}\text{C} + 3 \text{ mW} * 92^{\circ}\text{C/W} = 85.276^{\circ}\text{C}$ . 
10.  $T_J = T_C + P_D * \theta_{JC}$ , where:  $T_C$  is the Case Temperature, etc.

### **Table 7. A.C. TEST CONDITIONS**

Input Levels	0.2 V <sub>CC</sub> to 0.8 V <sub>CC</sub>
Input Rise and Fall Times	≤ 50 ns
Input Reference Levels	0.3 V <sub>CC</sub> , 0.7 V <sub>CC</sub>
Output Reference Levels	0.5 V <sub>CC</sub>
Output Load	Current Source: $I_{OL}$ = 3 mA ( $V_{CC}$ $\geq$ 2.5 V); $I_{OL}$ = 1 mA ( $V_{CC}$ < 2.5 V); $C_L$ = 100 pF

<sup>7.</sup> Tested initially and after a design or process change that affects this parameter.

<sup>8.</sup> t<sub>PU</sub> is the delay between the time V<sub>CC</sub> is stable and the device is ready to accept commands.

### Power-On Reset (POR)

The CAT34C02 incorporates Power–On Reset (POR) circuitry which protects the internal logic against powering up in the wrong state.

The CAT34C02 will power up into Standby mode after  $V_{CC}$  exceeds the POR trigger level and will power down into Reset mode when  $V_{CC}$  drops below the POR trigger level. This bi-directional POR feature protects the device against 'brown-out' failure following a temporary loss of power.

### **Pin Description**

**SCL**: The Serial Clock input pin accepts the Serial Clock generated by the Master.

**SDA**: The Serial Data I/O pin receives input data and transmits data stored in EEPROM. In transmit mode, this pin is open drain. Data is acquired on the positive edge, and is delivered on the negative edge of SCL.

 $A_0$ ,  $A_1$  and  $A_2$ : The Address pins accept the device address. These pins have on-chip pull-down resistors.

**WP**: The Write Protect input pin inhibits all write operations, when pulled HIGH. This pin has an on-chip pull-down resistor.

### **Functional Description**

The CAT34C02 supports the Inter-Integrated Circuit ( $I^2C$ ) Bus data transmission protocol, which defines a device that sends data to the bus as a transmitter and a device receiving data as a receiver. Data flow is controlled by a Master device, which generates the serial clock and all START and STOP conditions. The CAT34C02 acts as a Slave device. Master and Slave alternate as either transmitter or receiver. Up to 8 devices may be connected to the bus as determined by the device address inputs  $A_0$ ,  $A_1$ , and  $A_2$ .

### I<sup>2</sup>C Bus Protocol

The  $I^2C$  bus consists of two 'wires', SCL and SDA. The two wires are connected to the  $V_{CC}$  supply via pull-up resistors. Master and Slave devices connect to the 2-wire bus via their respective SCL and SDA pins. The transmitting

device pulls down the SDA line to 'transmit' a '0' and releases it to 'transmit' a '1'.

Data transfer may be initiated only when the bus is not busy (see A.C. Characteristics).

During data transfer, the SDA line must remain stable while the SCL line is HIGH. An SDA transition while SCL is HIGH will be interpreted as a START or STOP condition (Figure 2).

### Start

The START condition precedes all commands. It consists of a HIGH to LOW transition on SDA while SCL is HIGH. The START acts as a 'wake-up' call to all receivers. Absent a START, a Slave will not respond to commands.

### Stop

The STOP condition completes all commands. It consists of a LOW to HIGH transition on SDA while SCL is HIGH. The STOP starts the internal Write cycle (when following a Write command) or sends the Slave into standby mode (when following a Read command).

### **Device Addressing**

The Master initiates data transfer by creating a START condition on the bus. The Master then broadcasts an 8-bit serial Slave address. The first 4 bits of the Slave address are set to 1010, for normal Read/Write operations (Figure 3). The next 3 bits,  $A_2$ ,  $A_1$  and  $A_0$ , select one of 8 possible Slave devices. The last bit,  $R/\overline{W}$ , specifies whether a Read (1) or Write (0) operation is to be performed.

### Acknowledge

After processing the Slave address, the Slave responds with an acknowledge (ACK) by pulling down the SDA line during the 9<sup>th</sup> clock cycle (Figure 4). The Slave will also acknowledge the byte address and every data byte presented in Write mode. In Read mode the Slave shifts out a data byte, and then releases the SDA line during the 9<sup>th</sup> clock cycle. If the Master acknowledges the data, then the Slave continues transmitting. The Master terminates the session by not acknowledging the last data byte (NoACK) and by sending a STOP to the Slave. Bus timing is illustrated in Figure 5.

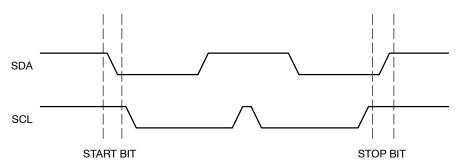


Figure 2. Start/Stop Timing

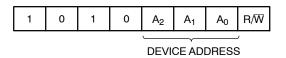


Figure 3. Slave Address Bits

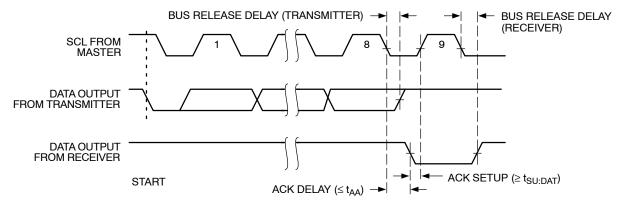


Figure 4. Acknowledge Timing

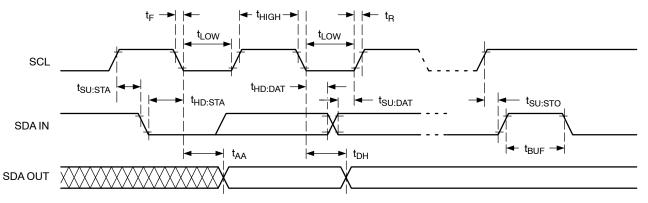


Figure 5. Bus Timing

### **Write Operations**

### **Byte Write**

In Byte Write mode the Master sends a START, followed by Slave address, byte address and data to be written (Figure 6). The Slave acknowledges all 3 bytes, and the Master then follows up with a STOP, which in turn starts the internal Write operation (Figure 7). During internal Write, the Slave will not acknowledge any Read or Write request from the Master.

### **Page Write**

The CAT34C02 contains 256 bytes of data, arranged in 16 pages of 16 bytes each. A page is selected by the 4 most significant bits of the address byte following the Slave address, while the 4 least significant bits point to the byte within the page. Up to 16 bytes can be written in one Write cycle (Figure 8).

The internal byte address counter is automatically incremented after each data byte is loaded. If the Master transmits more than 16 data bytes, then earlier bytes will be overwritten by later bytes in a 'wrap-around' fashion (within the selected page). The internal Write cycle starts immediately following the STOP.

### **Acknowledge Polling**

Acknowledge polling can be used to determine if the CAT34C02 is busy writing or is ready to accept commands. Polling is implemented by interrogating the device with a 'Selective Read' command (see READ OPERATIONS).

The CAT34C02 will not acknowledge the Slave address, as long as internal Write is in progress.

### **Delivery State**

The CAT34C02 is shipped 'unprotected', i.e. neither SWP flag is set. The entire 2 kb memory is erased, i.e. all bytes are FFh.

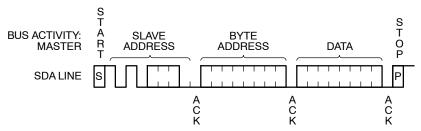


Figure 6. Byte Write Timing

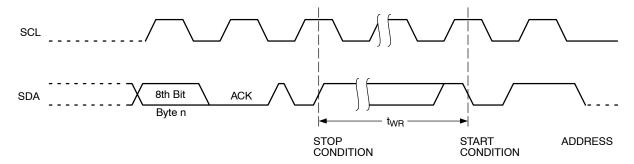


Figure 7. Write Cycle Timing

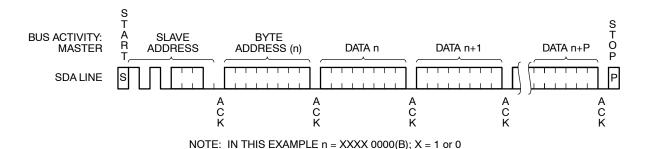


Figure 8. Page Write Timing

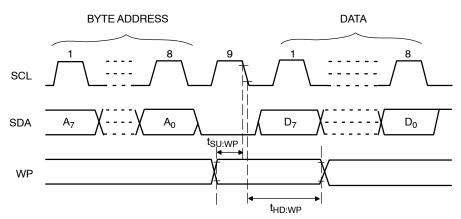


Figure 9. WP Timing

### **Read Operations**

### **Immediate Address Read**

In standby mode, the CAT34C02 internal address counter points to the data byte immediately following the last byte accessed by a previous operation. If that 'previous' byte was the last byte in memory, then the address counter will point to the 1st memory byte, etc.

When, following a START, the CAT34C02 is presented with a Slave address containing a '1' in the  $R/\overline{W}$  bit position (Figure 10), it will acknowledge (ACK) in the  $9^{th}$  clock cycle, and will then transmit data being pointed at by the internal address counter. The Master can stop further transmission by issuing a NoACK, followed by a STOP condition.

### **Selective Read**

The Read operation can also be started at an address different from the one stored in the internal address counter.

The address counter can be initialized by performing a 'dummy' Write operation (Figure 11). Here the START is followed by the Slave address (with the  $R/\overline{W}$  bit set to '0') and the desired byte address. Instead of following up with data, the Master then issues a  $2^{nd}$  START, followed by the 'Immediate Address Read' sequence, as described earlier.

### **Sequential Read**

If the Master acknowledges the 1<sup>st</sup> data byte transmitted by the CAT34C02, then the device will continue transmitting as long as each data byte is acknowledged by the Master (Figure 12). If the end of memory is reached during sequential Read, then the address counter will 'wrap-around' to the beginning of memory, etc. Sequential Read works with either 'Immediate Address Read' or 'Selective Read', the only difference being the starting byte address.

A C K

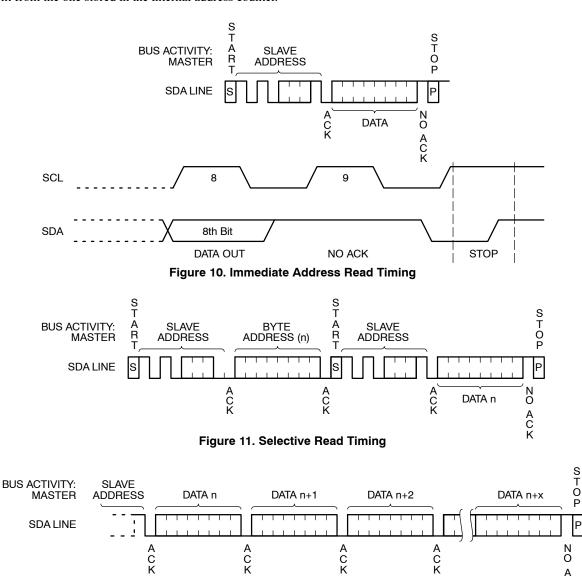


Figure 12. Sequential Read Timing

### **Software Write Protection**

The lower half of memory (first 128 bytes) can be protected against Write requests by setting one of two Software Write Protection (SWP) flags.

The Permanent Software Write Protection (PSWP) flag can be set or read while all address pins are at regular CMOS levels (GND or  $V_{\rm CC}$ ), whereas the very high voltage  $V_{\rm HV}$  must be present on address pin  $A_0$  to set, clear or read the Reversible Software Write Protection (**RSWP**) flag. The D.C. OPERATING CONDITIONS for RSWP operations are shown in Table 8.

The SWP commands are listed in Table 9. All commands are preceded by a START and terminated with a STOP, following the ACK or NoACK from the CAT34C02. All SWP related Slave addresses use the pre–amble: 0110 (6h), instead of the regular 1010 (Ah) used for memory access. For **PSWP** commands, the three address pins can be at any logic level, whereas for **RSWP** commands the address pins must be at pre–assigned logic levels. V<sub>HV</sub> is interpreted as logic '1'. The V<sub>HV</sub> condition must be established on pin A<sub>0</sub> before the START and maintained just beyond the STOP. Otherwise an RSWP request could be interpreted by the CAT34C02 as a PSWP request.

The SWP Slave addresses follow the standard I<sup>2</sup>C convention, i.e. to read the state of the SWP flag, the LSB of the Slave address must be '1', and to set or clear a flag, it must be '0'. For Write commands a dummy byte address and dummy data byte must be provided (Figure 14). In contrast to a regular memory Read, a SWP Read does not return Data. Instead the CAT34C02 will respond with NoACK if the flag

is set and with ACK if the flag is not set. Therefore, the Master can immediately follow up with a STOP, as there is no meaningful data following the ACK interval (Figure 15).

### **Hardware Write Protection**

With the WP pin held HIGH, the entire memory, as well as the SWP flags are protected against Write operations, see Memory Protection Map below. If the WP pin is left floating or is grounded, it has no impact on the operation of the CAT34C02.

The state of the WP pin is strobed on the last falling edge of SCL immediately preceding the first data byte (Figure 9). If the WP pin is HIGH during the strobe interval, the CAT34C02 will not acknowledge the data byte and the Write request will be rejected.

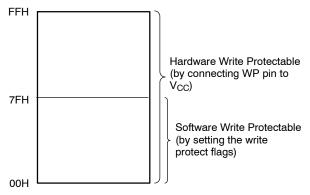


Figure 13. Memory Protection Map

Table 8. RSWP D.C. OPERATING CONDITIONS (Note 11)

Symbol	Parameter	Test Conditions	Min	Max	Units
$\Delta V_{HV}$	A <sub>0</sub> Overdrive (V <sub>HV</sub> – V <sub>CC</sub> )	$1.7 \text{ V} < \text{V}_{\text{CC}} < 3.6 \text{ V}$	4.8		V
I <sub>HVD</sub>	A <sub>0</sub> High Voltage Detector Current			0.1	mA
V <sub>HV</sub>	A <sub>0</sub> Very High Voltage		7	10	V
I <sub>HV</sub>	A <sub>0</sub> Input Current @ V <sub>HV</sub>			1	mA

<sup>11.</sup> To prevent damaging the CAT34C02 while applying  $V_{HV}$ , it is strongly recommended to limit the power delivered to pin  $A_0$ , by inserting a series resistor (> 1.5 k $\Omega$ ) between the supply and the input pin. The resistance is only limited by the combination of  $V_{HV}$  and maximum  $I_{HVD}$ . While the resistor can be omitted if  $V_{HV}$  is clamped well below 10 V, it nevertheless provides simple protection against EOS events. As an example:  $V_{CC} = 1.7 \text{ V}$ ,  $V_{HV} = 8 \text{ V}$ ,  $1.5 \text{ k}\Omega < R_S < 15 \text{ k}\Omega$ .

**Table 9. SWP COMMANDS** 

Action	Co	Control Pin Levels (Note 12)		1 3			Slave Address			ave Address		ACK	Address	ACK	Data	ACK	Write
Action	WP	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	PSWP	RSWP	b <sub>7</sub> to b <sub>4</sub>	b <sub>3</sub>	b <sub>2</sub>	b <sub>1</sub>	b <sub>0</sub>	?	Byte	?	Byte	?	Cycle
	Х	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	1	Х		A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	Χ	No					
Set	GND	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	0	X		A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	0	Yes	Х	Yes	Х	Yes	Yes
PSWP	V <sub>CC</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	0	X		A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	0	Yes	Х	Yes	Х	No	No
	Х	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	0	Х		A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>	1	Yes					
	Х	GND	GND	V <sub>HV</sub>	1	Х		0	0	1	Х	No					
0-4	Х	GND	GND	V <sub>HV</sub>	0	1		0	0	1	Х	No					
Set RSWP	GND	GND	GND	V <sub>HV</sub>	0	0	0110	0	0	1	0	Yes	Х	Yes	Х	Yes	Yes
	V <sub>CC</sub>	GND	GND	$V_{HV}$	0	0		0	0	1	0	Yes	Х	Yes	Х	No	No
	Х	GND	GND	$V_{HV}$	0	0		0	0	1	1	Yes					
	Х	GND	V <sub>CC</sub>	V <sub>HV</sub>	1	Х		0	1	1	Χ	No					
Clear	GND	GND	V <sub>CC</sub>	V <sub>HV</sub>	0	Х		0	1	1	0	Yes	Х	Yes	Х	Yes	Yes
RSWP	V <sub>CC</sub>	GND	V <sub>CC</sub>	$V_{HV}$	0	Х		0	1	1	0	Yes	Х	Yes	Х	No	No
	Х	GND	$V_{CC}$	$V_{HV}$	0	Х		0	1	1	1	Yes					

<sup>12.</sup> Here  $A_2$ ,  $A_1$  and  $A_0$  are either at  $V_{CC}$  or GND. 13.1 stands for 'Set', 0 stands for 'Not Set', X stands for 'don't care'.

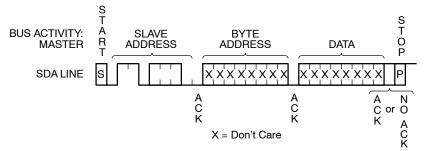


Figure 14. Software Write Protect (Write)

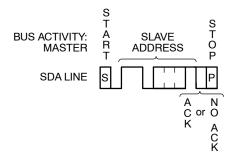
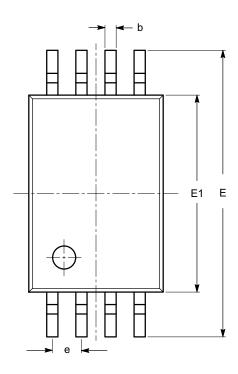


Figure 15. Software Write Protect (Read)

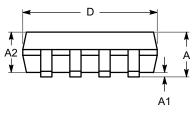
### **PACKAGE DIMENSIONS**

TSSOP8, 4.4x3 CASE 948AL-01 ISSUE O

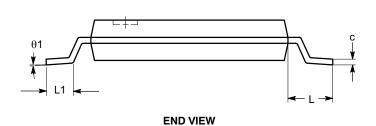


SYMBOL	MIN	NOM	MAX
Α			1.20
A1	0.05		0.15
A2	0.80	0.90	1.05
b	0.19		0.30
С	0.09		0.20
D	2.90	3.00	3.10
Е	6.30	6.40	6.50
E1	4.30	4.40	4.50
е		0.65 BSC	
L		1.00 REF	·
L1	0.50	0.60	0.75
θ	0°		8°

### **TOP VIEW**



SIDE VIEW

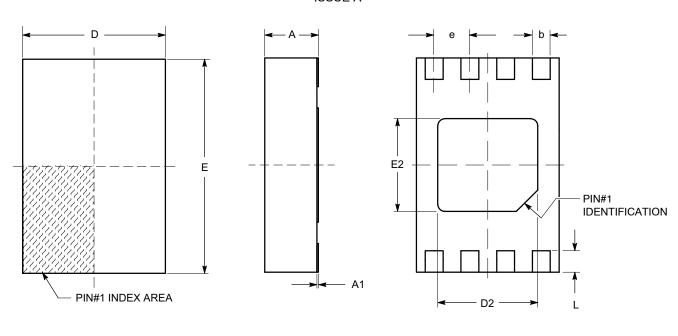


### Notes:

- (1) All dimensions are in millimeters. Angles in degrees.(2) Complies with JEDEC MO-153.

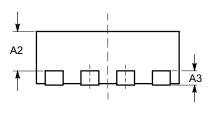
### **PACKAGE DIMENSIONS**

TDFN8, 2x3 CASE 511AK-01 ISSUE A



**SIDE VIEW** 

SYMBOL	MIN	NOM	MAX				
Α	0.70	0.75	0.80				
A1	0.00	0.02	0.05				
A2	0.45	0.55	0.65				
А3	0.20 REF						
b	0.20	0.25	0.30				
D	1.90	2.00	2.10				
D2	1.30	1.40	1.50				
Е	2.90	3.00	3.10				
E2	1.20	1.30	1.40				
е	0.50 TYP						
L	0.20	0.20 0.30 0.40					



**BOTTOM VIEW** 

FRONT VIEW

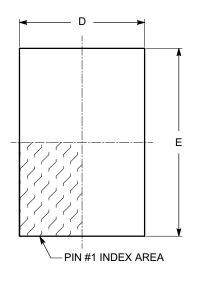
### Notes:

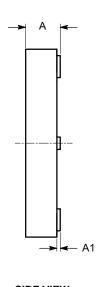
- (1) All dimensions are in millimeters.
- (2) Complies with JEDEC MO-229.

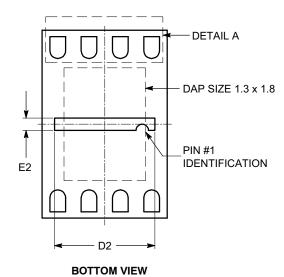
**TOP VIEW** 

### **PACKAGE DIMENSIONS**

**UDFN8, 2x3** CASE 517AX-01 ISSUE O





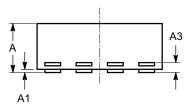


TOP V	/IEW
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**SIDE VIEW** 

SYMBOL	MIN	NOM	MAX
Α	0.45	0.50	0.55
A1	0.00	0.02	0.05
А3	0.127 REF		
b	0.20	0.25	0.30
D	1.90	2.00	2.10
D2	1.50	1.60	1.70
E	2.90	3.00	3.10
E2	0.10	0.20	0.30
е	0.50 TYP		
К	0.10 REF		
L	0.30	0.35	0.40

# **DETAIL A**



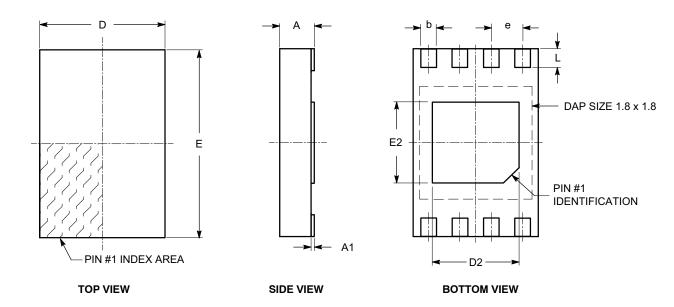
- (1) All dimensions are in millimeters.(2) Complies with JEDEC MO-229.

**FRONT VIEW** 

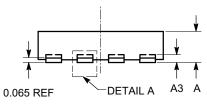
### **PACKAGE DIMENSIONS**

### **UDFN8, 2x3 EXTENDED PAD**

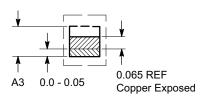
CASE 517AZ-01 ISSUE O



SYMBOL	MIN	NOM	MAX
Α	0.45	0.50	0.55
A1	0.00	0.02	0.05
A3	0.127 REF		
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D2	1.35	1.40	1.45
E	2.95	3.00	3.05
E2	1.25	1.30	1.35
Ф	0.50 REF		
L	0.25	0.30	0.35



**FRONT VIEW** 



**DETAIL A** 

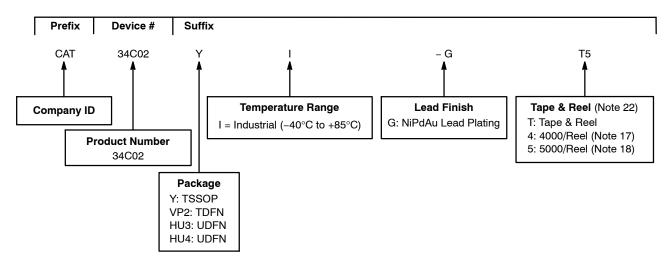
### Notes:

- (1) All dimensions are in millimeters.(2) Refer JEDEC MO-236/MO-252.

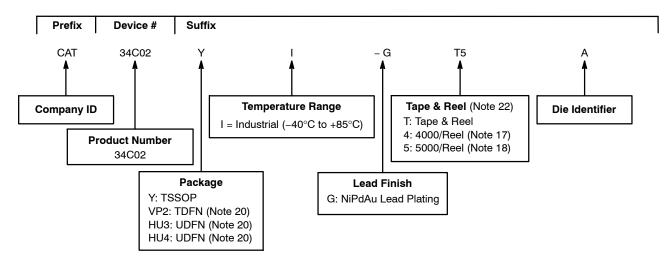
1. ALL DIMENSIONS ARE IN MILLIMETERS.

### **Example of Ordering Information**

### CAT34C02 MATURE PRODUCT (Note 16)



### CAT34C02 NEW PRODUCT (Note 19)



- 14. All packages are RoHS-compliant (Lead-free, Halogen-free)
- 15. The standard lead finish is NiPdAu.
- 16. The device used in the above example is a CAT34C02YI-GT5 mature product (TSSOP, Industrial Temperature, NiPdAu, 5000 pcs / Reel)
- 17. The TDFN and UDFN packages are available in 4000 pcs/Reel (i.e., CAT34C02VP2I-GT4, CAT34C02HU3I-GT4, CAT34C02HU3I-GT
- 18. The TSSOP (Y) package (i.e., CAT34C02YI-GT5) is available in 5000 pcs / Reel.
- 19. The CAT34C02 new product orderable part number requires the letter "A" added at the end of the OPN.
- 20. For the TDFN (VP2) and UDFN (HU3, HU4) packages of CAT34C02 new product, there is NO hyphen in the orderable part number (example: CAT34C02VP2IGT4A)
- 21. For additional package and temperature options, please contact your nearest ON Semiconductor Sales office.
- 22. For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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CAT34C02/D